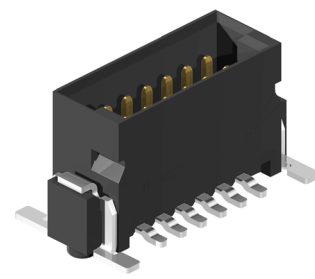
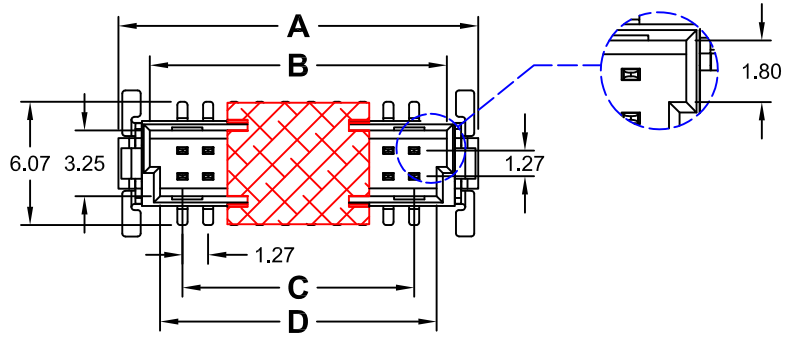
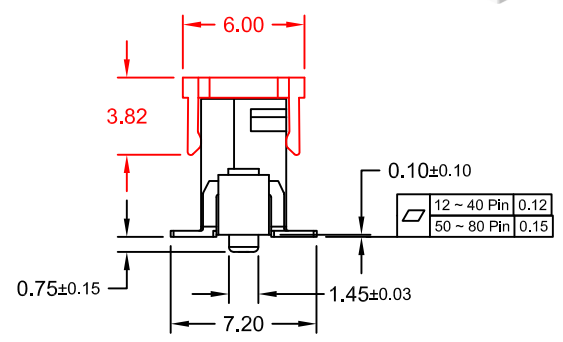
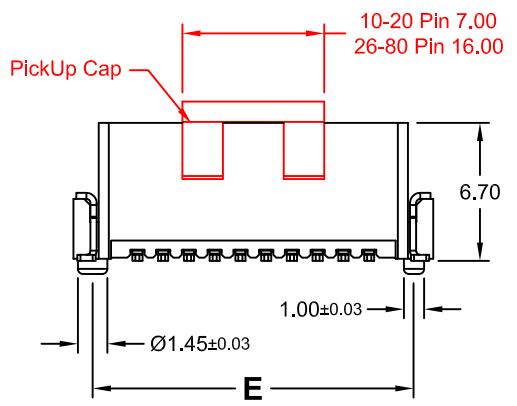


REV.	DESCRIPTION	DATE	DRAWN
A	New	05.12.2013	Ronny
D	add 10P & 20P	10.12.2018	RH
E	Design and solder feet improvement	18.12.2018	RH
F	separate datasheet for 8.20mm height	23.01.2019	Ronny

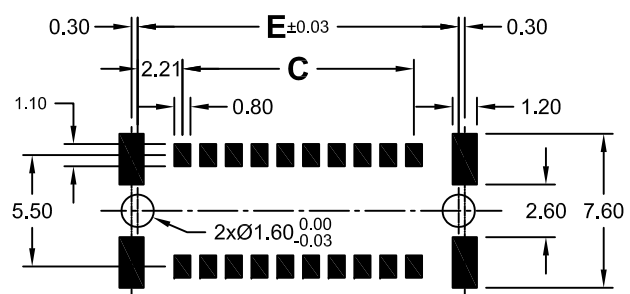


**Order Code**  
**MBC-xxx-QMV67-xx/11E**

**Plating**  
**95** = Tin/Gold flash  
**9L5** = Tin/ 3µ" Gold  
**96** = Tin/10µ" Gold  
**97** = Tin/15µ" Gold  
**98** = Tin/30µ" Gold



No. of Pins	Dimension mm				
	A	B	C	D	E
010	11,43	8,30	5,08	7,30	9,50
012	12,70	9,57	6,35	8,57	10,77
016	15,24	12,11	8,89	11,11	13,31
020	17,78	14,65	11,43	13,65	15,85
026	21,59	18,46	15,24	17,46	19,66
030	24,13	21,00	17,78	20,00	22,20
032	25,40	22,27	19,05	21,27	23,47
040	30,48	27,35	24,13	26,35	28,55
050	36,83	33,70	30,48	32,70	34,90
068	48,26	45,13	41,91	44,13	46,33
080	55,88	52,75	49,53	51,75	53,95



Recommended PCB Layout Top View  
(Tolerance ±0.05)



**Specifications**

**Electrical**  
Current rating: 0.5 ~ 1.0A  
Insulation resistance: 10000MΩ min.  
Contact resistance: 25mΩ max.  
Withstanding voltage: 500V

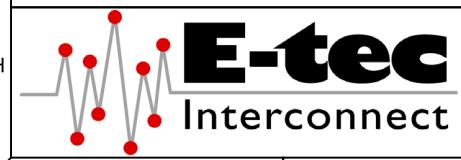
**Material**

Contact: Phosphor Bronze  
Plating: Tin on solder, Gold on contact area  
Insulator: LCP (black) UL 94V-0

Operating temperature: -55°C to +125°C  
Processing temperature: +260°C +0/-5°C  
for 5 seconds

**Packing:** Reel with PickUp Cap

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UNIT mm	GENERAL TOLERANCE		DRAWN Ronny	DATE 05.12.2013	DWG. NO. MBC-QMV67/11	SHEET 1/1
	X.° ±	X. ±	CHECK Hogi	DATE 23.01.2019	REV. F	Multi BUS/Backplane Connector <b>Q-Type Male SMT vertical</b> 1.27mm pitch - height 6,70mm <i>compatible to ERNI INTERact® Series SMC Type</i>
	.X° ±	.X ±	APPROVE Hogi	DATE 23.01.2019	SERIES NO. MBC-xxx-QMV67-xx/11E	
	.XX° ±	.XX ± 0.25				
.XXX° ±	.XXX ±					
SCALE Free						

